U.S. DEPARTMENT OF COMMERCE ATTY. DOCKET NO. SERIAL NO. PATENT AND TRADEMARK OFFICE M122-2362 10/625,068 TOF ART CITED BY APPLICANT (Use several sheets if necessary) APPLICANT Arup Bhattacharyya FILING DATE July 22, 2003 GROUP 2824 U.S. PATENT DOCUMENTS Date Class Subclass Filing Date *Examiner Document Name Initial Number If Appropriate 6,593,624 B2 07/03 Walker 257 344 COW 6,204,608 B1 03/01 169.3 COW Song et al. 315 AC ΑD ΑE AF AG ΑH Αl ΑJ ΑK AL FOREIGN PATENT DOCUMENTS Subclass Translation Document Date Country Number Yes ΑM AN ΑO ΑP AQ OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.) AR AS

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